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CO-004	Square Magazine for DIP	B	May 1978
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CO-007	Pin Grid Array Pkg., .100" Centers	A	October 1987
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DO-204 AJ-AM	Lead Mounted Family (Round Lead Axial)	C	July 1997
DO-204 AN-AR	Lead Mounted Family (Round Lead Axial)	B	July 1985
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MO-001 AE-AH	Dual in-line Family 7.62 mm Row Spacing	D	June 1976
MO-001 AJ-AM	Dual in-line Family 7.62 mm Row Spacing	F	June 1983
MO-001 AN-AP	Dual in-line Family 7.62 mm Row Spacing	B	October 1980
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MO-002 AJ-AL	Header Family .200" Pin Circle	C	October 1976
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MO-004 AL	<b>Replaced by MS-033 Variation AC</b>	A	November 1999
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MO-005	Grid Array Family, .125" Pitch	B	Archived – JEP 95
MO-006 AA-AD	Header Family 5.842 mm Pin Circle	C	October 1976
MO-006 AE-AH	Header Family 5.842 mm Pin Circle	D	October 1976
MO-007	Header Family, .141" Pin Circle	B	Archived – JEP 95
MO-008	Header Family, .100" Pin Circle	B	Archived – JEP 95
MO-009 AA-AB	Header Family, .200 Pin Circle	C	Archived – JEP 95
MO-010	Header Family, .065" Pitch	B	Archived – JEP 95
MO-011	Grid Array Family, 2.54 mm Pitch	B	Archived – JEP 95
MO-012 AA-AB	Quad Header Family, 2.54 mm Pitch	C	Archived – JEP 95
MO-013	Header Family, 11.89 mm Pin Circle	B	Archived – JEP 95
MO-014	Flange-Mounted Family Axial Lead	C	October 1976
MO-015 AA-AD	Dual In Line (DIP) Family 15.24 mm Row Spacing	D	June 1976
MO-015 AE-AH	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	June 1977
MO-015 AJ-AM	Dual In Line (DIP) Family 15.24 mm Row Spacing	E	February 1981
MO-015	R-PDIP-T Dual Inline Plastic Family .600" Row Spacing	G	April 1993
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MO-019 AB	<b>Replaced by MS-033 Variation AF</b>	A	November 1999
MO-019 AC	<b>Replaced by MS-033 Variation AE</b>	A	November 1999
MO-019 AD	<b>Replaced by MS-033 Variation AF</b>	A	November 1999
MO-019 AE	Flatpack Family 10.16 mm Width, 1.27 Pitch	D	November 1999
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MO-021	Flatpack Family 15.24 mm Width, 1.27 Pitch	C	June 1976
MO-022 AA-AD	Flatpack Family 17.780 mm Width, 1.27 Pitch	D	September 1977
MO-022 AE	Flatpack Family 17.780 mm Width, 1.27 Pitch	A	September 1977
MO-023	Flatpack Family 22.86 mm Width, 1.27 Pitch	C	June 1976
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MO-025	Flange Mounted Family Axial Lead 12.70 Pin Circle	B	October 1976
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MO-027	Leadless Flatpack Family 1.27 mm Terminal Space	A	February 1977
MO-028	Dual In Line (DIP) Family 5.08 mm Row Spacing	B	October 1976
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MO-030	Quad In Line (QUIP) Family 19.05/23.50 mm Row Spacing	B	October 1976
MO-031	Quad In Line (QUIP) Family 5.08/10.16 mm Row Spacing	D	October 1979
MO-032 AA-AF	Flatpack Family 16.64 mm Width, 1.27 Pitch	C	February 1981
MO-033	Quad In Line (QUIP) Family 17.78/22.86 mm Row Spacing	B	February 1981
MO-034	Quad In Line (QUIP Family) .750/.925" Row Spacing	C	June 1990
MO-035	Single In Line (SIP) Family	A	September 1980
MO-036	Ceramic Dual-In-Line (DIP) Family .300" Row Spacing	B	November 1999
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MO-039	Ceramic Side Ledged Dual In Line (DIP) Family 22.86 mm Row Spacing	A	April 1981
MO-040	Power Module	C	May 1983
MO-041 AA-AF	.050" Pitch Leadless Rectangular Chip Carrier Family (R-CQCC-N)	C	February 1995
MO-042	.050" Center Leadless Rectangular Chip Carrier Type F	A	February 1983



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MO-045	Single In Line Power Module	A	September 1984
MO-046	Small Outline (SO) Package Peripheral Terminals 5.30 mm (.200") Wide Body	B	November 1984
MO-047	Plastic Chip Carrier (PCC) Family .050" Leadspring, Square	B	November 1988
MO-048	Plastic Flange-Mounted Header Family Multilead Registration	A	February 1987
MO-049	<b>Not Published</b>		
MO-050	<b>Not Published</b>		
MO-051	<b>Not Published</b>		
MO-052	<b>Replaced by MS-016</b>		
MO-053	<b>Replaced by MO-069</b>		September 1988
MO-054	Zig-Zag (ZIP) In Line Family 2.54mm Row Spacing	A	June 1986
MO-055	Ceramic Single In Line (SIP) Family	A	August 1986
MO-056	Ceramic .025" Center Chip Carrier	A	August 1986
MO-057	Ceramic .020" Center Chip Carrier	A	August 1986
MO-058 AA	<b>Replaced by MS-030 AF</b>		
MO-058 AB	<b>Replaced by MS-030 AG</b>		
MO-059	Small Outline (SO) Package Family 8.4 mm Body Width (Plastic)	B	January 1987
MO-060	.040" 132 Pin Quad Flatpack	B	November 1989
MO-061	<b>Replaced by MS-027</b>		June 1995
MO-062	Ceramic Chip Carrier 0.25" Center	A	April 1987
MO-063	Plastic Small Outline J-Lead (SOJ) .350" Body	A	April 1987
MO-064	30 Circuit Pluggable Single Inline Package (SIP) Tabs on .100" Centers	C	September 1992
MO-065	Plastic Small Outline J-Lead (SOJ) .300 Body Family	A	May 1987
MO-066	S-CPGA-P Pin Grid Array Family, .100" Pitch (Small Outline)	C	April 1994
MO-067	Pin Grid Array Family, .100" Pitch (Large Outline), S-CPGA-P	B	June 1993
MO-068	Edge Clip SIP Module Family .100 Row Centers	B	August 1991
MO-069	Plastic Quad Flat Pack .025" Lead Spacing (Gullwing)	B	October 1990
MO-070	.375" Width Flatpack <b>NOT PUBLISHED</b>	A	August 1987
MO-071	Plastic Thin Lead Package	B	July 1989
MO-072	Zig-Zag Inline Family (ZIP) 0.500" Max Seated Height	B	September 1990
MO-073	Ceramic Top Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing	A	November 1987

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MO-074	Ceramic Bottom Brazed Dual In Line (DIP) Family .900 (22.86) Row Spacing	A	November 1987
MO-075	.50 Center Non-Hermetic Leadless Chip Carrier Quad Series	A	December 1987
MO-076	.050 Center Non-Hermetic Leadless Chip Carrier SO Series	A	December 1987
MO-077	Plastic Small Outline J-Lead Package Family (SOJ), .300" Wide Body, .050" Lead Pitch	D	November 1994
MO-078	Hermetic Flange-Mounted Header Family (Peripheral Terminals) Five Lead 2.54 Spacing	A	February 1988
MO-079	Flanged Family Peripheral lead .125 Pitch	A	March 1988
MO-080 AA-AB	ZIP Module Family 0.050" Pin Centers 0.100" Row Centers	A	September 1988
MO-081	Ceramic Quadpack Family .050" Pitch	A	March 1988
MO-082	Ceramic Quad Flat Pack .025" Lead Spacing (Gullwing)	A	May 1988
MO-083	.100" Center Plastic Pin Grid Array Family	A	December 1988
MO-084	Ceramic Quad Flat Pack 0.50" Lead Spacing (Gullwing)	A	July 1988
MO-085	.040" Center Rectangular Leadless Package (Staggered Terminals)	A	July 1988
MO-086	Low Profile Plastic Quad Flat Pack Family .025 Lead Spacing (Gullwing)	B	June 1990
MO-087	"J" Leaded Ceramic Cerquad Package Family - .050" Pitch	B	August 1991
MO-088 AA-AF	Small Outline J-Lead (SOJ) .300 Body Family (MS-113 body)	A	June 1988
MO-089	Plastic Quad Flat Pack .050" Lead Spacing (Gullwing)	A	November 1988
MO-090 AA-AF	Ceramic Quadpack Family .025" Lead Spacing	B	September 1989
MO-091	Plastic Small Outline J-Lead (SOJ) .350 Body Family	A	February 1989
MO-092	6.35 Mm Width Cerpak Registration	A	April 1989
MO-093	Flange-Mounted Header, 5-Lead	A	February 1990
MO-094	Molded Carrier Ring Family	C	March 1993
MO-095	Dual Incline (Wide Body) Plastic Family .300" Row Spacing	A	September 1989
MO-096	Flange-Mounted Header, 7-Lead	A	February 1990
MO-097	Flange-Mounted Family Axial Lead .500" Pin Circle	A	July 1989
MO-098	Braze Lead Flatpack Registration	A	December 1989
MO-099	Small Outline (SO) Family Peripheral	A	October 1989
MO-100	Multilayer Ceramic Quad Flatpack .20 Spacing	A	November 1989

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	Gullwing (256 leads)		
MO-101	48 Pin Flatpack, Top Brazed	A	November 1989
MO-102	Tape Quad Flatpack <b>RESCINDED</b>	A	November 1992
MO-103	<b>Replaced by MS-032</b>	B	August 1999
MO-104	Ceramic Quad Flatpack, 0.25" Pitch, Gullwing Leadform	A	August 1991
MO-105	Thin Small Outline J-Lead (TSOJ) .300" Body, 0.050" Lead Pitch	A	August 1990
MO-106	Flatpack Family .535" Length, .030 Pitch	A	April 1990
MO-107	Ceramic Multilayer Leded Chip Carrier .050" Pitch, J-Bend	A	May 1990
MO-108	Metric Plastic Quad Flat Pack Family, 1.0, 0.8, 0.65 Pitch PQFP-G/MQFP	C	August 1996
MO-109	Molded Carrier Ring Family	B	March 1993
MO-110	Round Lead, "J" form .050" Center Ceramic Chip Carrier	A	July 1990
MO-111	Round Lead, Gullwing .050" Center Ceramic Chip Carrier	A	July 1990
MO-112	Metric Plastic Quad Flatpack Family 3.9 mm Footprint	B	September 1995
MO-113	Ceramic Quadpack Family 0.25" Lead Spacing With Ceramic Nonconductive Tie Bar	D	August 1997
MO-114	Glass Sealed CQFP Family (GQFP-G)	C	January 1996
MO-115	32 Ld. Flatpack .480" Wide	A	November 1990
MO-116	Pluggable Single In-Line Memory Module (SIMM) With Tabs on .050 Centers	B	June 1998
MO-117	Small Outline Gullead 12 mm Body 0.80 mm Lead Spacing	A	June 1990
MO-118	Shrink Small Outline Package Family, 0.25" Lead Pitch .300" Wide Body Width (R-PDSO-G)	B	June 1993
MO-119	Plastic Small Outline (SO) Package Family With .300" Body Width	B	May 1992
MO-120	Plastic Small Outline (SO) Package Family With .350" Body Width	B	May 1992
MO-121	Plastic Small Outline (SO) Package Family With .330" Body Width	B	May 1992
MO-122	R-PDIP-T Thin Dual In Line Family .300" Row Spacing (Plastic)	A	August 1992
MO-123	Small Outline J-Lead, 12 mm Body 0.80 mm Lead Spacing	A	June 1991
MO-124	Small Outline J-Lead Package Family (SOJ) 12.70 mm Body, 1.27 mm Lead Spacing	B	January 1994

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MO-125	Ceramic Quad Flatpack .025" Pitch Gullwing Leadform	A	June 1991
MO-126	R-CDCC-N Leadless Small Outline Ceramic Chip Carrier .400" Body, .050" Pitch	B	June 1993
MO-127	Power Dual In-line	A	February 1992
MO-128 AA-BQ	.100" Center Staggered Pin Grid Array Family (Large Outline)	C	January 1997
MO-129	Top Brazed Ceramic Leaded Chip Carrier (.020" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-130	Top Brazed Ceramic Leaded Chip Carrier (.015" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-131	Top Brazed Ceramic Leaded Chip Carrier (.025" Lead Pitch) with Plastic Non-Conductive Tie Bar	A	September 1992
MO-132	<b>Replaced by MS-025A</b>		
MO-133	<b>Replaced by MS-024</b>		January 1995
MO-134	Ceramic Quad Flatpack Family (CQFP) 0.50 mm Lead Pitch with Ceramic Nonconductive Tie Bar	A	May 1992
MO-135	Thin Small Outline Package 12.70 mm Body Family (R-PDSO-G/TSOP II)	C	November 1993
MO-136	<b>Replaced by MS-026</b>		
MO-137	Plastic Shrink Small Outline Package (SSOP) Family 0.025" pitch 0.150" Body Width	E	March 2010
MO-138	16 Lead Flange Mounted Ceramic Power Package (Type 1), R-CDFM-T16	A	June 1993
MO-139	16 Lead Flange Mounted Ceramic Power Package (Type 2), R-CDFM-T16	A	June 1993
MO-140	18 Lead Flange Mounted Ceramic Power Package, R-CDFM-T16	A	June 1993
MO-141	Vertical Surface Mount Package 0.50 mm Lead Pitch, R-PSIP-X24	A	March 1993
MO-142	Thin Small Outline Package Type I, R-PDSO-G/TSOPII	D	July 2000
MO-143	<b>Replaced by MS-029</b>		June 1997
MO-144	Leadless Small Outline Ceramic Chip Carrier .350" Body, .050" Pitch, R-CDCC-N	A	June 1993
MO-145	S-CPGA-B/SMTPGA .050 Center Ceramic Surface Mount Pin Grid Array Family Registration	A	June 1993
MO-146	Ceramic Flatpack Family .380" Width, .025 Pitch (R-GDFP-F)	A	July 1993
MO-147	Small Outline J-Lead Ceramic Chip Carrier .415" Body, .050" Lead Spacing (R-CDSO-J)	A	July 1993

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MO-148	Multichip Module Ceramic Quad Flatpack (S-CQFP)	A	June 1993
MO-149	Tape Ball Grid Array Family	F	October 2003
MO-150	Plastic Shrink Small Outline Package (SSOP) - 5.3mm Body Width, 0.65mm Pitch, 1.25mm Lead Length (R-PDSO-G)	B	January 1994
MO-151	<b>Replaced by MS-034</b>		
MO-152	Plastic Shrink Small Outline Package (SSOP), R-PSDO-G/SSOP	C	January 1996
MO-153	Plastic Thin Shrink Small Outline Package (SSOP) R-PDSO-G/TSSOP/HTSSOP	G	January 2018
MO-154	Shrink Small Outline Package Family, 0.4 mm and .5 mm Lead Pitch, 3.9 mm Wide Body	C	April 1997
MO-155	5-Lead Small Outline Plastic (SOP) Package	A	November 1993
MO-156	Square Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch	C	April 2005
MO-157	Rectangular Ceramic Ball Grid Array Family 1.00, 1.27, and 1.50 mm Pitch	C	April 2005
MO-158	CBGA-X Ceramic Column Grid Array Family - Square	D	April 2002
MO-159	Ceramic Column Grid Array Family - Rectangular	B	June 1999
MO-160 AA-CC	72-Contact Dual Inline Memory Module (DIMM) Family, 1.27 Lead Centers	B	September 1995
MO-161	100 and 168 Pin Dual Inline Memory Module (DIMM) Family with Multiple Keyways, 1.27 mm Contact Centers	Ff	January 2003
MO-162	Plastic Flat Pack/Heat Slug Package 8 mm Pitch 48 Leads (S-PTFP-G48)	A	November 1993
MO-163	<b>Replaced by MS-028</b>		December 1997
MO-164	Plastic Small Outline Package, 9.90 mm Wide Body Family (R-PDSO-G)	A	January 1994
MO-165	Plastic Small Outline J-Lead, 10.15mm Body Family, .8mm Pitch	C	September 1996
MO-166 AA-AF	Plastic Small Outline Heat Slug Package, 20, 24, 30, 36 Leads	D	November 1999
MO-167	Pluggable Dual Inline Module, 1.27 mm Lead Centers 128-Pins	C	October 1997
MO-168 AA-AB	Plastic Isolated Flange-Mounted Header Family	A	January 1994
MO-169	Plastic Surface Mounted Header Family	B	November 2000
MO-170	68-Pin Card	A	February 1995
MO-171	88-Pin Card	A	February 1995

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MO-172	Dual Inline Memory Module (DIMM) Family 112 & 300 Pin 1.27 mm Pitch	D	April 1999
MO-173	TFH-PQFP-G/TQHS Thin Quad Heat Spreader Family Registration	A	October 1995
MO-174	Plastic Small Outline Package, 70-pin .8 mm Pitch (R-PDSO-G/SOP)	A	January 1996
MO-175	Plastic Small Outline Package, 12.6 mm Body, 1.27 mm Lead Spacing	A	September 1995
MO-176	Ceramic Zig-Zag Inline Family (2.54 Row Spacing)	A	March 1995
MO-177	200 Pin Small Outline Dual Inline Memory Module (DIMM) Family, 0.65 mm Lead Centers	A	July 2001
	<b>RESCINDED</b>		
MO-178	Plastic Small Outline Package (SOT/SP), 5 Leads	C	February 2000
MO-179	Dual Inline Memory Module (DIMM) Family 1.00 Lead Centers (278-pin)	A	October 1995
MO-180	Plastic Small Outline Package (SOP) 13.3 mm Body Width	B	February 2001
MO-181	Metric Small Outline 16 mm Wide Body J-Lead Package (MSOJ)	A	January 1996
MO-182	Metric Thin Small Outline 16.00 mm Wide Body Package (MTSOP II)	C	September 1996
MO-183	Thin Small Outline Package Type I 0.55 mm Lead Pitch (TSOP I)	A	January 1996
MO-184	Plastic Small Outline Heat Slug Package	B	November 1999
MO-185	72 Pin Staggered Dual Inline Module (SDIM) Family, 1.27 Lead Centers	A	August 1996
MO-186	Solid State Floppy Disk Card (SSFDC)	C	March 1999
MO-187	Plastic Thin Shrink Small Outline Package 0.65 & 0.50 Pitch	F	September 2010
MO-188	Power PQFP Heat Slug Package (H-PQFP - G)	B	February 2000
MO-189	Plastic Quad Flat Heat Slug Package (2.0mm Thick 2.00 mm Footprint Quad & Dual-Sided Leads)	A	March 1996
MO-190	Small Outline Dual Inline Memory Module (DIMM) Family, 0.8 Lead Centers	D	January 2001
MO-191	Dual Inline Memory Module (DIMM) Family 1.27 Lead Centers, 160 Leads	A	December 1996
MO-192	Low Profile Ball Grid Array Family	F	August 2003
MO-193	Plastic Thin Shrink Small Outline Package (Shrink SOT)	E	July 2013
MO-194	Plastic Thin Shrink Small Outline Package 0.40mm Lead Pitch	B	November 1997
MO-195	Thin Fine Pitch Ball Grid Array, 0.50mm Pitch	D	May 2006

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<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-196	Plastic Ultra-Thin Small Outline No-Lead Package	C	June 1998
MO-197	Plastic Ultra-Thin Small Outline No-Lead Package	B	November 1997
MO-198	PQFP-B 3-Tier Family	A	April 1997
MO-199	Low Profile Small Outline J-Lead Package (LSOJ)	B	June 1999
MO-200	Small Outline J-Lead Package Assembly 2 High/4 High Stack	B	June 1999
MO-201	2 High/4 High Stacked TSOP II <b>INACTIVATION NOTICE</b>	A	June 2003
MO-202	Vertical Zig Zag Surface Mount Package 0.40mm Lead Pitch	A	March 1998
MO-203	Plastic Thin Shrink Outline Package (Shrink SOT)	C	August 2010
MO-204	Plastic Quad Flat Package Outline With Exposed Heat Sink	B	May 2001
MO-205	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80mm Pitch, (Sq. & Rect.)	F	April 2003
MO-206	Dual Inline Memory Module (DIMM) Family 184 Pin DDR 1.27mm Contact Centers	E	January 2006
MO-207	Square & Rectangular Die-Size Ball Grid Array Family	N	June 2013
MO-208	Plastic Thin Fine Pitch Quad Flat No Lead Package	C	November 2001
MO-209	Plastic Thin Shrink Small Outline No Lead Package	A	November 1998
MO-210	Fine Pitch Ball Grid Array Family Rectangular, 0.80 mm Pitch	O	June 2018
MO-211	Die Size Ball Grid Array	C	June 2004
MO-212	Rectangular Plastic Quad Flat Package Outline 1.0mm Thick Body 3.20 Footprint	A	November 1998
MO-213	Horizontal Staggered Surface Mount Package 0.40mm Lead Pitch	A	November 1998
MO-214	Micro Dual Inline Memory Module Family, 0.5mm Lead Centers	B	September 2002
MO-215	SDRAM Dual Inline Memory Module (DIMM) Family, 1.00 mm Contact Centers <b>INACTIVATION NOTICE</b>	A	November 2000
MO-216	Plastic Bottom Ball Grid Array Family, 0.80 mm Pitch Square Family	F	November 2018
MO-217	Very Very Thin Quad Bottom Terminal Chip Carrier Family	B	November 2001
MO-218	Plastic Flange-Mounted, Staggered Header Family	A	October 1999
MO-219	Low Profile, Fine Pitch, Ball Grid Array Family, 0.80 mm Pitch. (SQ.& RECT.)	G	January 2007
MO-220	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	K.01	August 2011

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MO-221	Extremely Thin Profile Two Row Cavity Down 0.50 mm Pitch Ball Grid Array Family	C	May 2001
MO-222	Very Thin Profile, Fine Pitch, Land Grid Array Family, 0.50/0.65 mm PITCH, SQ/RECT	B.01	December 2010
MO-223	Plastic Thin Shrink Small Outline Package (Shrink SOT)	A	April 2000
MO-224	200 Pin DDR S.O. DIMM 0.60 mm Lead Centers	E	November 2006
MO-225	Very Thin Profile, Fine Pitch, Ball Grid Array Family 0.50/0.65 mm Pitch, SQ/RECT	C	August 2007
MO-226	Plastic Small Outline Heatslug Package 7.5mm Body Wide, 1.0mm Lead Pitch	B	February 2001
MO-227	DDR SRAM DIMM 1.00 mm Contact Centers <b>INACTIVATION NOTICE</b>	A	May 2003
MO-228	Thin, Fine-Pitch Ball Grid Array Family, Dual Pitch	A	March 2001
MO-229	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Dual Flat No Lead Package	F	August 2012
MO-230	Plastic Small Outline with Exposed Heat Sink	A	March 2001
MO-231	Plastic Surface Mounted Header Family 21.50mm Body Width, 1.40mm LEAD PITCH	A	August 2001
MO-232	Low Profile Plastic Dual Flat No Lead Package	A	August 2001
MO-233	Rectangular Die-Size, Fine Dual Pitch Ball Grid Array Family	C	February 2003
MO-234	Bottom Grid Array, Ball, 1.00 mm Pitch Rectangular Family	E	June 2018
MO-235	Header Family Surface Mounted (Peripheral Terminals)	B	February 2003
MO-236	Plastic Ultra and Super Thin Small Outline, Non-Leaded Package	C	March 2010
MO-237	DDR2 SDRAM DIMM (Dual Inline Memory Module) Family 1.00mm Contact Centers	G.01	April 2011
MO-238	Stacked TSOP II Package Family (2 High)	A	February 2003
MO-239	Thermally Enhanced Plastic Very Thin Dual Row Fine Pitch Quad Flat No Lead Package	A	November 2002
MO-240	Thermally Enhanced 8 Lead 1.27 & 0.65MM Pitch, Low Profile Plastic Dual Flat No Lead Package	C	August 2012
MO-241	Dual Compatible Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package	B	August 2003
MO-242	Rectangular Die-Size, Stacked Ball Grid Array Family .80mm Pitch	C	September 2008
MO-243	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Bumped Quad Flat No lead	A	August 2003
MO-244	244 Pin DDR2 Mini DIMM 0.60 Lead Centers	C	February 2008



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MO-245	High Profile Plastic Thermally Enhanced Enlarged Pitch Dual Flat No Lead Package	A	September 2003
MO-246	Rectangular Fine Pitch Thin Ball Grid Array 0.65 mm Pitch	G	February 2015
MO-247	Plastic Quad No-Lead Staggered Multi-Row Packages	D	May 2007
MO-248	Thermally Enhanced Plastic Ultra Thin and Extremely Thin Fine Pitch Quad Flat No Lead Package	E	June 2006
MO-249	Thin SO Package 8.89mm Body Family	A	January 2004
MO-250	Thermally Enhanced Plastic Very Thin and Very Very Thin Fine Pitch Bumped Quad Flat No Lead Package	A	November 2003
MO-251	Thermally Enhanced Plastic Very Thick Quad Flat No Lead Package	A	February 2004
MO-252	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Dual Small Outline Non-Leaded Package	D	March 2010
MO-253	14 & 16 Lead Screw Mount and Surface Mount Power Package	B	February 2008
MO-254	Thermally Enhanced Plastic Low and Thin Profile Fine Pitch Quad Flat No Lead Package	A	February 2004
MO-255	Plastic Very Very Thin Ultra Thin and Extremely Thin Fine Pitch Quad Flat Small Outline Non-Leaded Package	B	October 2005
MO-256	FB DIMM Family 1.00mm Contact Centers	F	June 2007
MO-257	Plastic Fine Pitch Quad No-Lead Staggered Two Row Thermally Enhanced Package Family	B	May 2005
MO-258	200 PIN DDR Mini DIMM 0.60 Lead Centers	A	December 2004
MO-259	Very Very Thin Small Outline Package Family	A	March 2005
MO-260	DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	C	January 2007
MO-261	Thick & Very Thick Fine Pitch Rectangular Ball Grid Array Family 0.80mm Pitch	A	June 2005
MO-262	Thermal Enhanced (Top Side) Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	A	September 2005
MO-263	Plastic Very Thin and Very Very Thin Fine Pitch Quad Flat No Lead Package	A	September 2005
MO-265	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package Including Corner Terminals	A	November 2005

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OUTLINE NUMBER	TITLE	ISSUE LETTER	DATE
MO-266	Very Thin, Fine-Pitch, Stackable Ball Grid 0.50 mm Ball Pitch Array Family	C	January 2009
MO-267	Thermally Enhanced Plastic Very Thin Fine Pitch Quad Flat No Lead Package	B	March 2006
MO-268	204 Pin DDR3 S.O. DIMM 0.60 Lead Centers	E	March 2014
MO-269	DDR3 SDRAM DIMM 1.00mm Contact Centers	I	February 2014
MO-270	Extra Thin Profile, Fine Pitch, Internal Stacking Module (ISM) With Single Interconnect Array 0.75/0.80 mm Pitch SQ/RECT	B	June 2008
MO-271	Exposed Pad Plastic Small Outline Family 7.60 mm Body Width	A	May 2006
MO-272	Low Profile Exposed Pad Plastic Small Outline Family 3.90mm Body Width	A	May 2006
MO-273	Upper POP Package, Square, Fine Pitch, Ball Grid Array (0.65 and 0.50 mm Pitch)	C	March 2011
MO-274	DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family 0.8 Lead Centers	D	October 2014
MO-275	Low Profile, Fine Pitch Ball Grid Array Family (SQ)	A.01	July 2011
MO-276	Fine Pitch Ball Grid Array Family, Rectangular, 0.50mm Pitch FR-XBGA	N	June 2018
MO-277	13 Pin Full Size MultimediaCard (MMC) Outline- MMCplus 32 X 24 X 1.4mm	A	September 2006
MO-278	13 Pin Reduced Size MultimediaCard (MMC) Outline-MMCmobile 18 X 24 X 1.4mm	A	September 2006
MO-279	10 Pin Micro Size MultimediaCard (MMC) Outline- MMCmicro 14 X 12 X 1.1mm	A	September 2006
MO-280	Ultra Thin and Very, Very Thin Profile, Fine Pitch Ball Grid Array Family (SQ.)	A	September 2006
MO-281	DDR2 SDRAM DIMM (Dual Inline Memory Module ) Family, Flex-Based, 1.00mm Contact Centers	A	November 2006
MO-282	FB DIMM Family, Flex Based, 1.00 mm Contact Centers	A	January 2007
MO-283	Plastic Super-Thin And Die-Thin Profiles RFID Dipole Straps	B	January 2008
MO-284	Thin, Fine-Pitch, Rectangular Dual Pitch Ball Grid Array Family 0.80mm x 1.00mm Pitch	A	May 2007
MO-285	Very Thin Fine-Pitch Ball Grid Array Family Rectangular 0.50/0.65/0.80 mm Pitch	A	August 2007

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<b>OUTLINE NUMBER</b>	<b>TITLE</b>	<b>ISSUE LETTER</b>	<b>DATE</b>
MO-286	Plastic Small Outline, Wide Body SOIC, 7.5 Body Width, 0.65 Pitch	B	January 2015
MO-287	Small Scale, Plastic, Ultra, Extra and Super Thin, Fine Pitch, Dual Small Outline, No Lead Package	A	September 2007
MO-288	Small Scale Plastic Ultra Extra and Super Thin Fine Pitch Quad Flat No Lead Package (With Optional Thermal Enhancements)	B	September 2009
MO-290	DDR3 SDRAM DIMM Family Flex-Based, 1.00mm Contact Centers	A	November 2007
MO-291	Very Thin Fine Pitch Plastic Quad Flat Package 2.00mm Footprint	B	December 2008
MO-292	Very Thin Fine Pitch Plastic Quad Flat Package, 2.00mm Footprint	C	April 2010
MO-293	Plastic, Ultra, Extra and Super Thin Fine Pitch Dual Small Outline, Flat, Leaded Package	A	December 2008
MO-294	Very Thin Profile, Fine Pitch, SQ Bump Grid Array Family	A	December 2008
MO-295	Thin Profile Interstitial Fine Pitch Ball Grid Array Family (SQ)	A	January 2009
MO-296	Scalable Quad Flat No-Lead Packages, Square and Rectangular	B	January 2012
MO-297	SLIM LITE SSD Assembly	A	May 2009
MO-298	Thin, Very-Thin, Very Very Thin Profile Fine Pitch Ball Grid Array Family 0.40 mm Pitch	A	June 2009
MO-299	Surface Mount Power Package, Fused Leads	B	January 2015
MO-300	mSATA SSD Assembly	C	March 2015
MO-301	Standard & Low, Fine Pitch Rectangular BGA Family 0.65mm Pitch	A	May 2010
MO-302	Very Thin Fine-Pitch Fully Overmolded Stackable Ball Grid Array Family 0.4mm Ball Pitch	C	August 2016
MO-303	Land Grid Array, Rectangular, 0.5 mm Pitch	B	March 2012
MO-304	100/170 Ball Grid Array Family Rectangular 1.0mm Pitch	D	July 2013
MO-305	Wide I/O Micropillar Grid Array Package (MPGA)	C	October 2013
MO-306	Flange Mounted Family Surface Mount (Peripheral Terminals)	A	February 2011
MO-307	Dual-Pitch Rectangular BGA Package 0.50mm X 0.65mm Pitch	A	December 2011
MO-308	Thick Thermally Enhanced Fine Pitch Square BGA Family	A	April 2012
MO-309	288 Pin DDR4 DIMM 0.85mm Pitch	F	March 2015

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MO-310	256 Pin DDR4 SODIMM and GDDR5M Outline 0.50 mm Pitch	C	February 2014
MO-311	Dual-Pitch Very Thin Profile Rectangular Fine Pitch BGA Package 0.80 mm X 0.65 mm Pitch	D	December 2014
MO-312	4 Lead Flat and Gullwing Surface Mount Power Package	A	February 2013
MO-313	Fine Pitch BGA Family Square 0.50mm Pitch	A	August 2014
MO-314	288 Pin DDR4 Mini DIMM, 0.50mm Pitch	A.01	May 2015
MO-315	Dual Pitch Number BGA Family, Square, 0.80 mm Major, 0.65 mm Minor Pitch	A	February 2015
MO-316	HBM Micropillar Grid Array Package (MPGA)	B	April 2019
MO-317	Upper POP BGA Square 0.40MM Pitch	C	January 2018
MO-318	BGA, Square, 1.00 MM Pitch	B	January 2017
MO-319	6 Lead Surface Mount Power Package with Fused Leads	A	February 2016
MO-320	12 Pin UFS Card 0.91 MM Pitch	A	March 2016
MO-321	Upper PoP BGA Family Square 0.50 MM Pitch (S-XBGA)	A.01	March 2017
MO-322	Upper PoP BGA Family Square 0.65 MM Pitch (S-XBGA)	A.01	March 2017
MO-323	Upper PoP BGA Family Square 0.40 MM Pitch (R-XBGA)	A.01	March 2017
MO-324	Lower PoP BGA Family Square 0.50 MM Top 0.50 MM Bottom Pitch (S-XBGA)	A	August 2016
MO-325	Lower PoP BGA Family Square 0.65 MM Top 0.50 MM Bottom Pitch (S-XBGA)	A	August 2016
MO-326	Lower PoP BGA Family Square 0.80 MM Top 0.50 MM Bottom Pitch (S-XBGA)	A	August 2016
MO-327	9 Lead Surface Mount Power Package, 1.2 mm Pitch H-PSOF	A	September 2016
MO-328	Ball Grid Array Family, Rectangle, 0.755 mm Pitch	A	January 2017
MO-329	288 Pin DDR5 DIMM, 0.85 MM Pitch	A	August 2017
MO-330	Ball Grid Array Family Rectangular, 0.60 mm x 0.70 mm Pitch PDSO-F2	A	June 2018
MO-331	Bottom Grid Array Ball, Square, 1.00 mm Pitch	A	June 2018
MO-332	Plastic Multi Small Outline, 17 Terminal, 1.20 mm Pitch Package. PMSO-E17	A	August 2018
MO-333	Plastic Bottom Flatpack 35 Terminal Package. PQFP-N35	A	August 2018
MO-334	Plastic Single Sided Hardware 7 Wire 1.2 mm Pitch Package. P-PSXH-W7_I120	A	September 2018

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MO-336	Plastic Bottom Grid Array, Ball 0.70 mm Pitch, Square Family	A	November 2018
MO-337	262 Pin SODIMM, 0.50 mm Pitch Package	A	April 2019
MO-338	Plastic Bottom Grid Array Ball, 0.80 MM x 0.70 MM Pitch Rectangular Family Package	A	September 2019
MO-339	Plastic Bottom Flatpack 28 Terminal Package	A	September 2019
MO-340	Plastic Dual Small Outline Surface Terminal, Wettable Flank Package	A	October 2019
MO-341	Plastic Quad Flatpack, 8 Terminal, 1.27 mm Pitch Package	A	October 2019

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SO-001	240 Pin DDRII SDRAM, 1.00mm Contact Centers	B	July 2003
SO-002	244 Pin MINIDIMM 0.60mm Lead Centers	B	February 2008
SO-003	FB DIMM 240 Position Socket Outline 1.00mm Contact Centers	B	August 2006
SO-004	Connector Outline for DDR and DDR2 Micro DIMM Mezzanine 214 Pin 0.4mm Lead Centers	A	May 2005
SO-005	200 Pin Mini DIMM 0.60 mm Lead Centers	A	September 2005
SO-006	204 Pin SO-DDR3 SDRAM, 0.60mm Contact Centers, Socket Outline	B	October 2007
SO-007	DDR3 DIMM 240 Position Socket Outline 1.00mm Contact Centers	B	September 2008
SO-008	144 Pin, DDR1/DDR2 16b/32b Small Outline Dual Inline Memory Module (SO-DIMM) Family, 0.8 Lead Centers, Dual Notch, Socket Outline	B	October 2012
SO-009	DDR2 DIMM 240 Pin SMT Socket Outline 1.00mm Contact Centers	A	March 2007
SO-011	240 Pin DDR2 DIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-012	240 Pin DDR3 DIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-013	240 Pin FBDIMM 1.00 mm Contact Centers Press Fit Socket Outline	A	September 2007
SO-014	DDR3 DIMM 240 Pin SMT Socket Outline 1.0 mm Contact Centers	A	July 2008
SO-015	mSATA SSD 0.80 mm Pitch	A	December 2011
SO-016	DDR4 DIMM PTH 284 Pin Socket Outline 0.8 MM Pitch	C	August 2014
SO-017	DDR4 DIMM SMT 284 Pin Socket Outline 0.85 MM Pitch	C	August 2014
SO-018	DDR4 and GDDR5M SODIMM 256 Pin Socket 0.50MM Pitch	C	July 2015
SO-019	DDR4 DIMM Press Fit 284 Pin SO 0.85 Pitch	C	August 2014
SO-021	DDR4 MiniDIMM SMT 288 Pin Socket Outline 0.50 mm Pitch	A	February 2015
SO-022	12 Pin UFS Socket Outline 0.91 MM Pith (SKT)	A	August 2016
SO-023	DDR5 DIMM SMT Pin Socket Outline 0.85 MM Pitch	B	July 2019
SO-024	262 Pin DDR5 SODIMM, 0.50 mm Pitch Socket	A	April 2019

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TO-1	Metal Can		Archived – JEP 95
TO-2	Metal Can		Archived – JEP 95
TO-3	Diamond Base, .430 Pin Spacing	A	Archived – JEP 95
TO-4	<b>MISSING</b>		
TO-5	Axial Leads, .200 Pin Circle	A	Archived - JEP 95
TO-6	Press Fit		Archived – JEP 95
TO-7	Metal Can		Archived – JEP 95
TO-8	Axial Leads, .281 Pin Circle	A	Archived – JEP 95
TO-9	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-10	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-11	Metal Can with Flange		Archived – JEP 95
TO-12	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-13	Metal Can with Rigid Terminals		Archived – JEP 95
TO-14	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-15	Stud-Mount, Rigid Terminals		Archived – JEP 95
TO-16	Metal Can with Flange		Archived – JEP 95
TO-17	4 Axial Leads .071 Pin Circle		Archived – JEP 95
TO-18	Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-19	<b>MISSING</b>		
TO-20	<b>MISSING</b>		
TO-21	<b>MISSING</b>		
TO-22	Flat Metal Can with Flange		Archived – JEP 95
TO-23	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-24	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-25	Cylindrical Metal Can with Flange		Archived – JEP 95
TO-26	Stud-Mounted Metal Can with Flange		Archived – JEP 95
TO-27	Diamond Flange with Holes and Rigid Leads		Archived – JEP 95
TO-28	Metal Can with Flange		Archived – JEP 95
TO-29	Metal Can with Flange		Archived – JEP 95
TO-30	Metal Can with Flange		Archived – JEP 95
TO-31	Metal Can with Stud Mount		Archived – JEP 95
TO-32	Metal Can with Stud Mount		Archived – JEP 95
TO-33	4 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-34	<b>MISSING</b>		
TO-35	<b>MISSING</b>		
TO-36	Stud-Mount .345 Pin Circle		Archived – JEP 95
TO-37	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-38	Cylindrical Metal Can with Flexible Leads		Archived – JEP 95
TO-39	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-40	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95

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TO-42	Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-43	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-44	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-45	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-46	Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-47	Cylindrical Metal Can with Flange and Flexible Leads		Archived – JEP 95
TO-48	Stud-Mount, Solid Leads	B	Archived – JEP 95
TO-49	Stud-Mount, Braided Terminal	B	Archived – JEP 95
TO-50	Strip Line Package		Archived – JEP 95
TO-51	Strip Line Package		Archived – JEP 95
TO-52	Axial Leads, .100 Pin Circle		Archived – JEP 95
TO-53	Flange-Mount, Rigid Leads		Archived – JEP 95
TO-54	Metal Can with Flange		Archived – JEP 95
TO-55	Metal Can with Flange		Archived – JEP 95
TO-56	Metal Can with Flange		Archived – JEP 95
TO-57	Stud-Mount, Flexible Leads		Archived – JEP 95
TO-58	Metal Can with Flange Mount		Archived – JEP 95
TO-59	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-60	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-61	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-62	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-63	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-64	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-65	Stud-Mount, Solid Terminals		Archived – JEP 95
TO-66	Diamond Base, .200 Pin Spacing	A	Archived – JEP 95
TO-67	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-68	Stud-Mount Metal Can with Rigid Leads		Archived – JEP 95
TO-69	Metal Can with Flange, 12 Leads		Archived – JEP 95
TO-70	Metal Can with Flange, 8 Leads		Archived – JEP 95
TO-71	8 Axial Leads .141 Pin Circle		Archived – JEP 95
TO-72	4 Axial Leads, .100 Pin Circle	A	Archived – JEP 95
TO-73	12 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-74	10 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-75	6 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-76	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-77	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-78	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95



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TO-80	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-81	Stud-Mount Metal Can with Flange		Archived – JEP 95
TO-82	Stud-Mount Metal Can with Flange		Archived – JEP 95
TO-83	Stud-Mount, Double End	B	Archived – JEP 95
TO-84	Multiple-Ended 14-Lead Flatpack	B	Archived – JEP 95
TO-85	Multiple-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-86	Multiple-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-87	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-88	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-89	Double-Ended 10-Lead Flatpack	B	Archived – JEP 95
TO-90	Double-Ended 10-Lead Flatpack	A	Archived – JEP 95
TO-91	Double-Ended 10-Lead Flatpack	A	Archived – JEP 95
TO-92	Axial Leaded, Flat Index	A	Archived – JEP 95
TO-93	Stud-Mount, Flex Leads	B	Archived – JEP 95
TO-94	Stud-Mount, Flex Leads	B	Archived – JEP 95
TO-95	Double-Ended 14-Lead Flatpack	A	Archived – JEP 95
TO-96	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-97	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-98	In-Line Axial Leads, Indexed	C	Archived – JEP 95
TO-99	8 Axial Leads, .200 Pin Circle	A	Archived – JEP 95
TO-100	10 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-101	12 Axial Leads, .230 Pin Circle	A	Archived – JEP 95
TO-102	Stud-Mount, Flex Leads		Archived – JEP 95
TO-103	Stud-Mount with Rigid Leads	A	Archived – JEP 95
TO-104	Metal Can with Tab, 4 Leads	A	Archived – JEP 95
TO-105	Epoxy Cylinder with Axial Leads	A	Archived – JEP 95
TO-106	Epoxy Cylinder with Axial Leads	A	Archived – JEP 95
TO-107	Metal Can with Flange, Cylindrical	A	Archived – JEP 95
TO-108	Stud-Mount with Flexible Terminals	A	Archived – JEP 95
TO-109	Flange-Mount with Terminals	A	Archived – JEP 95
TO-110	Epoxy with Axial Leads, 10 Leads	A	Archived – JEP 95
TO-111	Stud-Mount, Solid Leads	A	Archived – JEP 95
TO-112	Metal Can with Flange	A	Archived – JEP 95
TO-113	Strip Line with Metal Can	A	Archived – JEP 95
TO-114	Stud-Mount, 4 Solid Terminals	A	Archived – JEP 95
TO-115	Stud-Mount with Rigid Leads	A	Archived – JEP 95
TO-116	DIP, .300 Wide	A	Archived – JEP 95
TO-117	Lateral, 4 Flat Leads	A	Archived – JEP 95
TO-118	Stud-Mount, Flex Leads	A	Archived – JEP 95
TO-119	Strip Line Package , 3 Leads	A	Archived – JEP 95
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TO-122	Leadless Inverted Device	A	Archived – JEP 95
TO-123	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-124	Diamond Base, .200 Pin Circle	A	Archived – JEP 95
TO-125	Metal Can with Flange	A	Archived – JEP 95
TO-126	Flat Lead, .090 Pin Spacing	A	Archived – JEP 95
TO-127	Flat Lead, .166 Pin Spacing	A	Archived – JEP 95
TO-128	Stud-Mount, Lateral 4 Flat Leads	A	Archived – JEP 95
TO-129	Stud-Mount, Lateral 4 Flat Leads	A	Archived – JEP 95
TO-130	Strip Line Package, 4 Leads	A	Archived – JEP 95
TO-131	Strip Line Package, 4 Leads	A	Archived – JEP 95
TO-132	Stud-Mount with Flexible Leads	A	Archived – JEP 95
TO-200 AA-AD	Disc Type Family	I	April 1984
TO-200 AE-AF	Disc Type Family	J	July 1985
TO-201	Coaxial Family	B	Archived – JEP 95
TO-202	Tab-Mounted Peripheral Leads	F	February 1978
TO-203	Press-Fit Family - Solid Leads	C	Archived – JEP 95
TO-204 AA-AE	Flange-Mounted Header Family (.430) Pin Spacing	C	November 1982
TO-205	Header Type .200 Pin Circle	E	November 1982
TO-206	Header Type .100 Pin Circle	B	November 1982
TO-207	Stud-Header Family, .690 Pin Circle	A	Archived – JEP 95
TO-208 AA-AD	Stud Hex Base Family (Solid Terminals)	A	June 1974
TO-208 AE-AG	Stud Hex Base Family (Solid Terminals)	C	May 1979
TO-209	Stud-Hex, Flexible Terminals	A	June 1974
TO-210 AA-AE	Stud-Hex Base Family (Solid Terminals)	A	Archived – JEP 95
TO-211 MA-MB	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-212 MA	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-213	Flange-Mounted Header, .200 Spacing	A	September 1976
TO-214	Stud-Hex Base Family (Solid Leads)	A	Archived – JEP 95
TO-215	Coaxial Type	A	June 1971
TO-216	Stud-Mounted Stripline	A	June 1971
TO-217	Stud Rectangular Base Family	A	Archived – JEP 95
TO-218	Flange-Mounted Header	E	June 1986
TO-219	Flange-Mounted Header	B	December 1977
TO-220	Plastic Multi Position Flange Mount Mixed Technology 0.10 in Pitch Package	L	January 2019
TO-221 AA-AB	Flat-Mounted Peripheral Leads	A	Archived – JEP 95
TO-222 AA-AB	Header Family (.200 Pin Circle)	A	Archived – JEP 95
TO-223 AA-AB	Header Family (.100 Pin Circle)	A	Archived – JEP 95
TO-224 AA	Disc Family - Peripheral Leads	A	Archived – JEP 95
TO-225	Flat Mounted Family (Peripheral Terminals)	C	Archived – JEP 95
TO-226 AE	Header Family, Flat Index	A	December 1981

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TO-228 AA-AC	Stud-Mounted Family (Peripheral Terminals)	A	Archived – JEP 95
TO-229	Stripline Header Family	A	Archived – JEP 95
TO-230 AA-AB	Header Family	B	Archived – JEP 95
TO-231 AA-AB	Stud Hex-Base Family (.100 & .200 Pin Circle)	A	Archived – JEP 95
TO-232 AA-AC	Stud Mounted Radial Lead Family	A	Archived – JEP 95
TO-233	Header Family (.280 Pin Circle)	A	Archived – JEP 95
TO-234 AA-AD	Radial Lead Family	A	Archived – JEP 95
TO-235	Flange Mounted Header Family (.400 Pin Spacing)	A	Archived – JEP 95
TO-236	Plastic Small Outline Package (SOT/SOP), 3 Leads	H	January 1999
TO-237	Header Family, Flat Index	B	October 1979
TO-238	Flange-Mounted Header, Rectangular	D	March 1982
TO-239 AA-AB	Flange Mounted Header Family (Cylindrical Body) .490 Pin Circle	B	Archived – JEP 95
TO-240	Terminal Strip Power Module	B	March 1981
TO-241	Header Family(.100 Pin Circle)	A	Archived – JEP 95
TO-242	Header Family Flange Mounted (.100 Pin Circle)	A	Archived – JEP 95
TO-243	Header Family, Peripheral Terminal	C	July 1986
TO-244	Flange-Mounted Rectangular Base	B	September 1984
TO-245	Header Family, .100 Pin Circle <b>DRAWING NOT AVAILABLE</b>		
TO-246	Header Family, .200 Pin Circle <b>DRAWING NOT AVAILABLE</b>		
TO-247	Flange-Mounted Header Family	E	June 2004
TO-248	Power Module	A	Archived – JEP 95
TO-249	Flange Mounted Family (Rectangular Base)	B	Archived – JEP 95
TO-250	4-Lead DIP .300” Spacing	A	July 1985
TO-251	Header Family, Peripheral Terminals	D	June 2002
TO-252	Flange Mounted Family Surface Mount	F	January 2017
TO-253	Plastic Small Outline Package (SOT/SOP), 4 Leads	D	January 1999
TO-254	Flange-Mounted, Peripheral Leads	A	November 1986
TO-255	Disc Family, Peripheral Leads <b>Not Published</b>		December 1987
TO-256	Flat Mounted Transistor	A	March 1988
TO-257	Flange Mounted Header Family (Peripheral Terminals)	C	September 1996
TO-258	Flange-Mounted 5.08 Spacing	A	February 1988
TO-259	Flange-Mounted Header Family	B	April 1991
TO-260	Ceramic Header Axial 3-Lead	A	April 1989
TO-261	Plastic Small Outline Package SOP/SOT	C	May 2002
TO-262	Flange-Mounted Header Family	A	June 1990
TO-263	Plastic Surface Mounted Header Family	F	September 2013
TO-264	Header Family Insertion Mount (Peripheral Terminals)	B	November 1993
TO-265	3 Lead Flange Mounted Ceramic Power Package	A	June 1993

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TO-266	Opto Family Insertion Mount (Peripheral Terminals)	A	April 1994
TO-267	Hermetic Flange Mounted Header Family (Peripheral Terminals) Three Lead, 5.0 Spacing	A	September 1994
TO-268	Header Family Surface Mounted (Peripheral Terminals)	A	June 1995
TO-269	Small Outline Surface Mount (R-PDSO-G4)	A	August 1996
TO-270	Two Lead Surface Mount Power Package	C	July 2008
TO-271	Quad Flat Pack Surface Mount Thermally Enhanced	A	May 1998
TO-272	6-Lead Screw Mount Power Package	B	February 2004
TO-273	Plastic Flange Mounted Package, 3 Leads	B	July 2003
TO-274	Plastic Clip Mounted Package, 3 Leads	A	March 2000
TO-275	Plastic Flange Mounted Power Package, 2 Leads	A	November 2000
TO-276	Ceramic No Lead Chip Carrier	A	January 2001
TO-277	Small Outlines Plastic Surface Mount Package	A	January 2006
TO-278	Thin Profile, 3 Lead Plastic Small Outline Surface Mount	B	November 2006
TO-279	Plastic Surface Mounted Header Family	B	August 2008
TO-280	Flange Mounted Header Family	A	August 2010
TO-281	Fully Molded Flange Header Family Full-Pak	A	November 2011

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UO-002	16 Beam Chip	B	Archived – JEP 95
UO-003	18 Beam Chip	B	Archived – JEP 95
UO-004	20 Beam Chip	B	Archived – JEP 95
UO-005	22 Beam Chip	B	Archived – JEP 95
UO-006	24 Beam Chip	B	Archived – JEP 95
UO-007	26 Beam Chip	B	Archived – JEP 95
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UO-011	12 Beam Chip	B	Archived – JEP 95
UO-012	6 Beam Chip	B	Archived – JEP 95
UO-013	8 Beam Chip	B	Archived – JEP 95
UO-014	10 Beam Chip	B	Archived – JEP 95
UO-015	4 Beam Chip	B	Archived – JEP 95
UO-016	34 Beam Chip	A	Archived – JEP 95
UO-017	Tape Automated Bonding Uncased Outline	A	October 1988
UO-018	Tape Automated Bonding (TAB) Package Family	B	July 1993